

## **CLAIM AMENDMENTS**

Please amend claim 6 as follows:

Claims 1-5 (cancelled).

Claim 6 (currently amended): A circuit board for a semiconductor device, comprising:

a plurality of pads for the semiconductor device on which the semiconductor device is to be mounted, said pads being formed on the circuit board, and said pads being disposed only in a first line, which is in parallel to one of the sides of the circuit board;

a plurality of terminals for an external device formed on the ~~the~~ side edge of the circuit board, said terminals being disposed only in a second line, which is in parallel to said first line of said pads,

whereby no pads and terminals are formed in line along other sides of the circuit board, and the pads in the first line and the terminals in the second line are always in parallel;

a resist film covering an area on the circuit board between said pads and said terminals; and

a barrier formed between said first line of said pads and said second line of said terminals, said barrier including a plurality of line-shaped trench extending along said terminals, and said trenches being formed in said resist film,

wherein the entire surface of the circuit board in each trench is exposed in each trench.

Claim 7 (original): A circuit board for a semiconductor device as claimed in claim 6, wherein said trenches are parallel to each other.

Claims 8-12 (cancelled).

Claim 13 (previously presented): A circuit board for a semiconductor device as claimed in claim 6, wherein a distance between trenches is 1 mm.

Claim 14 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 15 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein a depth of the barrier equals the thickness of the resist film.

Claim 16 (previously presented): A circuit board for a semiconductor device as claimed in claim 6, wherein each trench had a width of 1 mm.

Claim 17 (previously presented): A circuit board for a semiconductor device as claimed in claim 16, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 18 (previously presented): A circuit board for a semiconductor device as claimed in claim 16, wherein a depth of the barrier equals the thickness of the resist film.

Claim 19 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein each trench had a width of 1 mm.

Claim 20 (previously presented): A circuit board for a semiconductor device as claimed in claim 19, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 21 (previously presented): A circuit board for a semiconductor device as claimed in claim 19, wherein a depth of the barrier equals the thickness of the resist film.